

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V_{IH}	Input HIGH Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		1.7	—	—	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		—	—	0.7	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		—	—	0.8	
I_{IH}	Input HIGH Current	$V_{CC} = 3.6\text{V}$	$V_I = V_{CC}$	—	—	± 5	μA
I_{IL}	Input LOW Current	$V_{CC} = 3.6\text{V}$	$V_I = \text{GND}$	—	—	± 5	
I_{OZH}	High Impedance Output Current (3-State Output pins)	$V_{CC} = 3.6\text{V}$	$V_O = V_{CC}$	—	—	± 10	μA
I_{OZL}			$V_O = \text{GND}$	—	—	± 10	μA
V_{IK}	Clamp Diode Voltage	$V_{CC} = 2.3\text{V}$, $I_{IN} = -18\text{mA}$		—	-0.7	-1.2	V
V_H	Input Hysteresis	$V_{CC} = 3.3\text{V}$		—	100	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	$V_{CC} = 3.6\text{V}$ $V_{IN} = \text{GND}$ or V_{CC}		—	0.1	40	μA
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at $V_{CC} - 0.6\text{V}$, other inputs at V_{CC} or GND		—	—	750	

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NOTE:

1. Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.

BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
I_{BHH}	Bus-Hold Input Sustain Current	$V_{CC} = 3.0\text{V}$	$V_I = 2.0\text{V}$	-75	—	—	μA
I_{BHL}			$V_I = 0.8\text{V}$	75	—	—	
I_{BHH}	Bus-Hold Input Sustain Current	$V_{CC} = 2.3\text{V}$	$V_I = 1.7\text{V}$	-45	—	—	μA
I_{BHL}			$V_I = 0.7\text{V}$	45	—	—	
I_{BHNO} I_{BHLO}	Bus-Hold Input Overdrive Current	$V_{CC} = 3.6\text{V}$	$V_I = 0$ to 3.6V	—	—	± 500	μA

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NOTES:

1. Pins with Bus-hold are identified in the pin description.

2. Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = 2.3V to 3.6V	I _{OH} = – 0.1mA	V _{CC} – 0.2	—	V
		V _{CC} = 2.3V	I _{OH} = – 4mA	1.9	—	
			I _{OH} = – 6mA	1.7	—	
		V _{CC} = 2.7V	I _{OH} = – 4mA	2.2	—	
			I _{OH} = – 8mA	2	—	
		V _{CC} = 3.0V	I _{OH} = – 6mA	2.4	—	
			I _{OH} = – 12mA	2	—	
V _{OL}	Output LOW Voltage	V _{CC} = 2.3V to 3.6V	I _{OL} = 0.1mA	—	0.2	V
		V _{CC} = 2.3V	I _{OL} = 4mA	—	0.4	
			I _{OL} = 6mA	—	0.55	
		V _{CC} = 2.7V	I _{OL} = 4mA	—	0.4	
			I _{OL} = 8mA	—	0.6	
		V _{CC} = 3.0V	I _{OL} = 6mA	—	0.55	
			I _{OL} = 12mA	—	0.8	

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NOTE:

1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = – 40°C to + 85°C.

OPERATING CHARACTERISTICS, T_A = 25°C

Symbol	Parameter	Test Conditions	V _{CC} = 2.5V ± 0.2V	V _{CC} = 3.3V ± 0.3V	Unit
			Typical	Typical	
C _{PD}	Power Dissipation Capacitance Outputs enabled	C _L = 0pF, f = 10Mhz	32	37	pF
C _{PD}	Power Dissipation Capacitance Outputs disabled		7	11.5	pF

SWITCHING CHARACTERISTICS ⁽¹⁾

Symbol	Parameter	V _{CC} = 2.5V ± 0.2V		V _{CC} = 2.7V		V _{CC} = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{MAX}		150	—	150	—	150	—	MHz
t _{PLH} t _{PHL}	Propagation Delay A _x to Y _x	1	4.4	—	4.5	1.1	3.9	ns
t _{PLH} t _{PHL}	Propagation Delay $\overline{\text{LE}}$ to Y _x	1	5.8	—	6	1.3	5	ns
t _{PLH} t _{PHL}	Propagation Delay CLK to Y _x	1	5.2	—	5.4	1	4.9	ns
t _{PZH} t _{PZL}	Output Enable Time $\overline{\text{OE}}$ to Y _x	1	6.4	—	6.4	1.1	5.4	ns
t _{PHZ} t _{PLZ}	Output Disable Time $\overline{\text{OE}}$ to Y _x	1	4.7	—	5.1	1.7	5	ns
t _w	Pulse Duration, $\overline{\text{LE}}$ LOW	3.3	—	3.3	—	3.3	—	ns
t _w	Pulse Duration, CLK HIGH or LOW	3.3	—	3.3	—	3.3	—	ns
t _{SU}	Setup Time, data before CLK↑	1.4	—	1.7	—	1.5	—	ns
t _{SU}	Setup Time, data before $\overline{\text{LE}}$ ↑, CLK HIGH	1.2	—	1.6	—	1.3	—	ns
t _{SU}	Setup Time, data before $\overline{\text{LE}}$ ↑, CLK LOW	1.4	—	1.5	—	1.2	—	ns
t _H	Hold Time, data after CLK↑	0.9	—	0.9	—	0.9	—	ns
t _H	Hold Time, data after $\overline{\text{LE}}$ ↑, CLK HIGH or LOW	1.2	—	1.1	—	1.1	—	ns
t _{SK(o)}	Output Skew ⁽²⁾	—	—	—	—	—	500	ps

NOTES:

1. See test circuits and waveforms. T_A = – 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

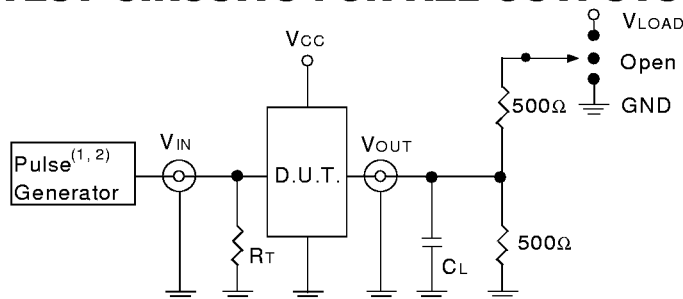
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1)= 3.3V±0.3V	V _{CC} (1)= 2.7V	V _{CC} (2)= 2.5V±0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



ALVC Link

DEFINITIONS:

C_L = Load capacitance; includes jig and probe capacitance.
R_T = Termination resistance; should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

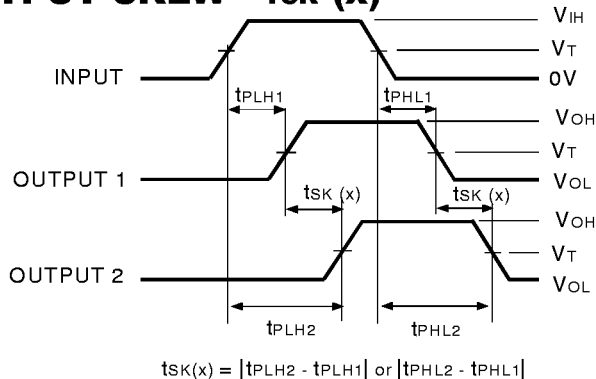
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

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OUTPUT SKEW - t_{SK} (x)



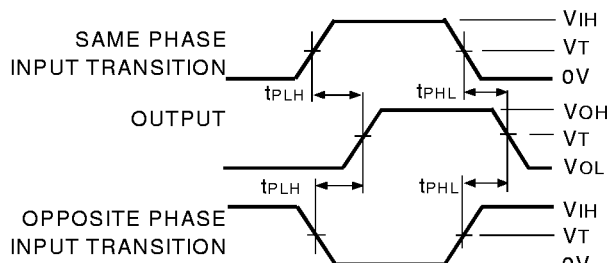
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

ALVC Link

NOTES:

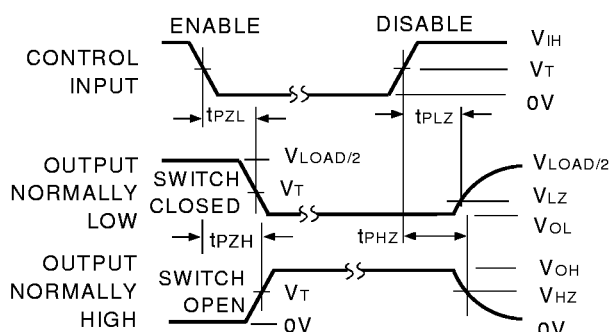
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



ALVC Link

ENABLE AND DISABLE TIMES

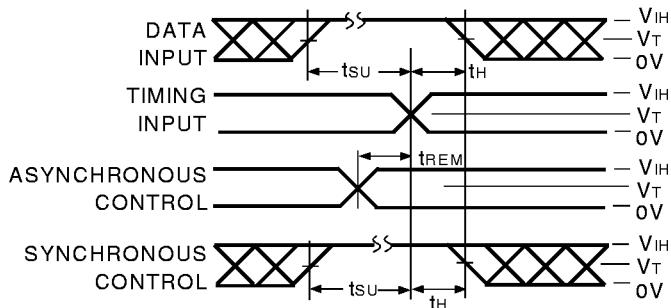


ALVC Link

NOTE:

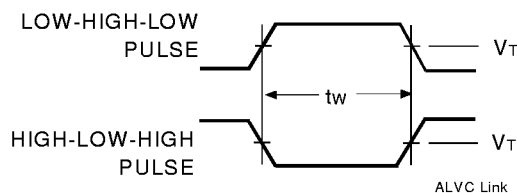
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



ALVC Link

PULSE WIDTH



ALVC Link

ORDERING INFORMATION

IDT	XX	ALVC	X	XX	XXX	XX	
	Temp. Range		Bus-Hold	Family	Device Type	Package	
						PV	Shrink Small Outline Package (SO48-1)
						PA	Thin Shrink Small Outline Package (SO48-2)
						PF	Thin Very Small Outline Package (SO48-3)
						334	16-Bit Universal Bus Driver with 3-State Outputs
						162	Double-Density with Resistors, $\pm 12\text{mA}$
						H	Bus-Hold
						74	-40°C to $+85^{\circ}\text{C}$



CORPORATE HEADQUARTERS

2975 Stender Way
 Santa Clara, CA 95054

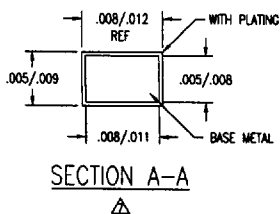
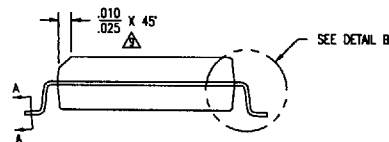
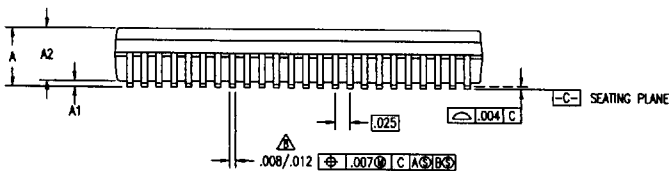
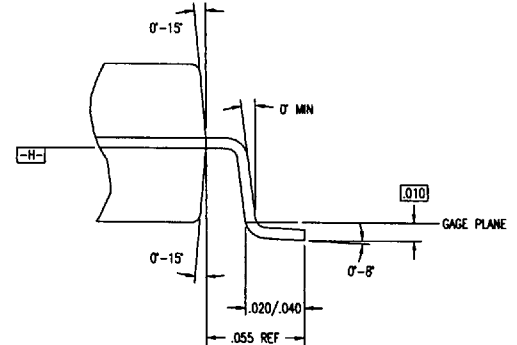
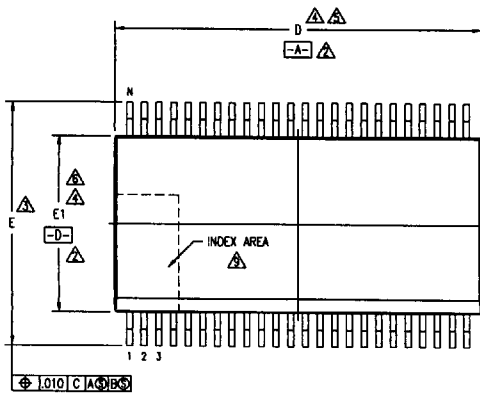
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 fax: 408-492-8674
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PACKAGE DIAGRAM OUTLINES
SSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Slender Way, Santa Clara, CA 95054	
XXX	±	PHONE: (408) 727-8118	
XXXS		FAX: (408) 482-8874	
XXXSS		TWC: 910-338-2070	
APPROVALS	DATE	TITLE	REV
DRAWN AA	08/15/90	PV PACKAGE OUTLINE	02
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE C	
		DRAWING No. PSC-4029	
		DO NOT SCALE DRAWING	

PACKAGE DIAGRAM OUTLINES SSOP (Continued)

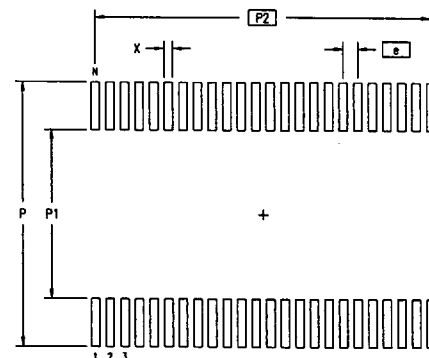
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WJ
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

DWG #		S048-1				DWG #		S056-1			
SYMBOL	JEDEC VARIATION				NOTE	JEDEC VARIATION				NOTE	
	AA			AB							
	MIN	NOM	MAX	MIN		NOM	MAX				
A	.095	.102	.110		.095	.102	.110				
A1	.008	.012	.016		.008	.012	.016				
A2	.088	.090	.092		.088	.090	.092				
D	.620	.625	.630	4,5	.720	.725	.730	4,5			
E	.395	.405	.420	3	.395	.405	.420	3			
E1	.291	.295	.299	4,6	.291	.295	.299	4,6			
N	48				56						

NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- ⚠ DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
- ⚠ DIMENSION E TO BE DETERMINED AT SEATING PLANE **-C-**
- ⚠ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **-H-**
- ⚠ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- ⚠ DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- ⚠ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- ⚠ LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- ⚠ THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- 10 ALL DIMENSIONS ARE IN INCHES
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

LAND PATTERN DIMENSIONS



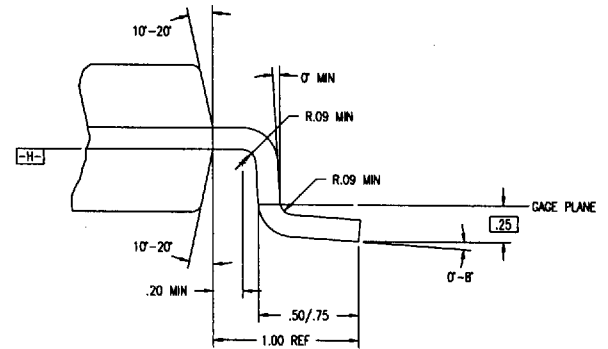
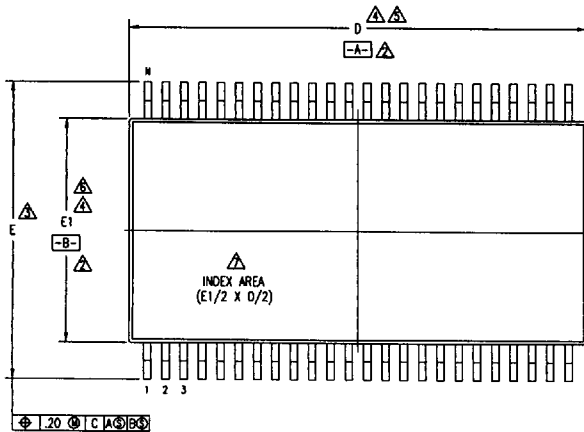
	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Stoner Way, Santa Clara, CA 95054	
X.XX	±	PHONE: (408) 727-8116	
X.XXX	±	FAX: (408) 482-8874	
X.XXX	±	TW: 810-338-2070	
APPROVALS	DATE	TITLE	REV
DRN	06/15/90	PV PACKAGE OUTLINE	
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE	REV
		C	02
		DRAWING No.	
		PSC-4029	
		DO NOT SCALE DRAWING	

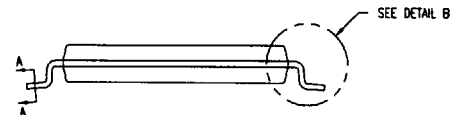
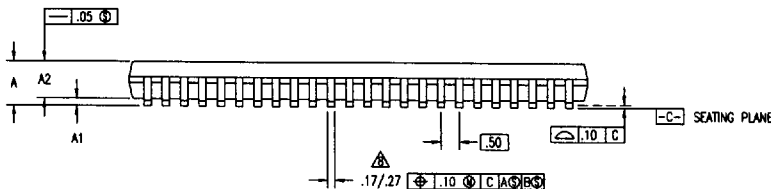
PACKAGE DIAGRAM OUTLINES

TSSOP

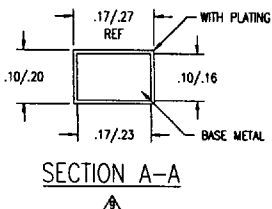
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	



DETAIL B



SEE DETAIL B



TOLERANCES UNLESS SPECIFIED			Integrated Device Technology, Inc.	
DECIMAL	ANGULAR		2975 Slender Way, Santa Clara, CA 95054	
XXX.X	±		PHONE: (408) 727-8118	
XXXX.X			FAX: (408) 492-8674 TWC 910-336-2070	
XXXXX				
APPROVALS	DATE	TITLE PA PACKAGE OUTLINE		
DRAWN	01/15/93	6.10 mm BODY WIDTH TSSOP		
CHECKED		.50 mm PITCH		
		SIZE	DRAWING No.	REV
		C	PSC-4039	03
DO NOT SCALE DRAWING				

PACKAGE DIAGRAM OUTLINES TSSOP (Continued)

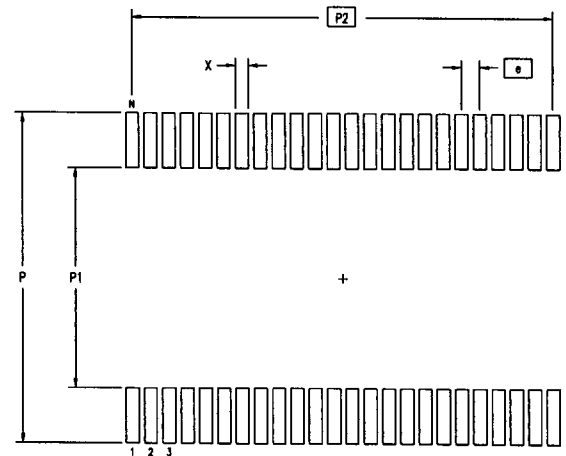
SYMBOL	DWG #			S048-2		NOTE	DWG #			S056-2		NOTE		
	JEDEC VARIATION						JEDEC VARIATION							
	ED						EE							
	MIN	NOM	MAX					MIN	NOM	MAX				
A	-	-	1.10				-	-	1.10					
A1	.05	-	.15				.05	-	.15					
A2	.85	1.00	1.05				.85	1.00	1.05					
D	12.40	12.50	12.60	4,5			13.90	14.00	14.10	4,5				
E	7.95	8.10	8.25	3			7.95	8.10	8.25	3				
E1	6.00	6.10	6.20	4,6			6.00	6.10	6.20	4,6				
N	48						56							

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS $\square$ -A- and $\square$ -B- TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION E TO BE DETERMINED AT SEATING PLANE $\square$ -C-
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- ALL DIMENSIONS ARE IN MILLIMETERS
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MQ-153, VARIATION ED & EE

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

LAND PATTERN DIMENSIONS



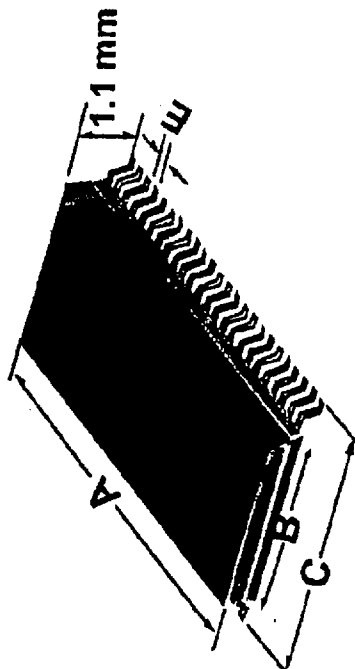
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P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50	BSC	13.50	BSC
X	.30	.40	.30	.40
e	.50	BSC	.50	BSC
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 PHONE: (408) 727-8118 FAX: (408) 482-8874 TWC: 910-338-2070	
DECIMAL	ANGULAR		
XXX.X	±	TITLE PA PACKAGE OUTLINE 6.10 mm BODY WIDTH TSSOP .50 mm PITCH	
APPROVALS	DATE		
DRAWN <i>AA</i>	01/19/93	SIZE C DRAWING No. PSC-4039	
CHECKED			
		DO NOT SCALE DRAWING	REV 03



TVSOP

The Most Compact Double Density Package

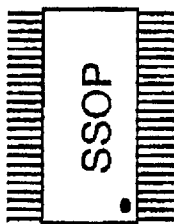


TVSOP Package	Typical Dimensions (in mm)				Area (mm ²)
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50



Double Density Packaging

48-Pin



16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²

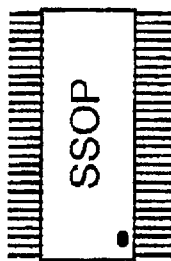


12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²



9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²

56-Pin



18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²



14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²



11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²

TVSOP	Area (mm ²)	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0